

ABSTRACT

OPTOELECTRONIC PART PRODUCING METHOD, OPTOELECTRONIC PART
PRODUCING SYSTEM, AND OPTOELECTRONIC PART

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Provided is a technique for facilitating the handling of a pre-sealed or sealed substrate so as to produce LED packages (or other types of optoelectronic parts) with high productivity. After a pre-sealed substrate 1 is fitted in a carrier 14, the carrier 14 is fixed to an upper die 18. Next, a lower die 17 and the upper die 18 are closed, whereby LED chips 13
10 mounted on the pre-sealed substrate 1 are immersed in a fluid resin 26 stored in the cavities of the lower die 17. Subsequently, the fluid resin 26 is hardened into a cured resin 28. Thus, the LED chips 28 are collectively sealed with resin. After that, the lower die 17 and the upper dies 18 are opened, and the carriers 14 with the sealed substrate 29 held therein is removed. Then, the sealed substrate 29 is pushed out of the carrier 14, and the sealed
15 substrate 29 is cut. As a result, the sealed substrate 29 is divided into individual LED packages each of which has one LED chip 13.

Fig. 3